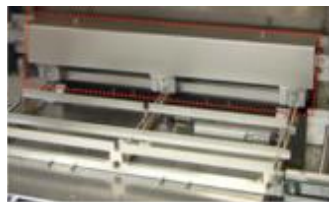


Vacuum Inline Reflow Vapour Phase Soldering Oven

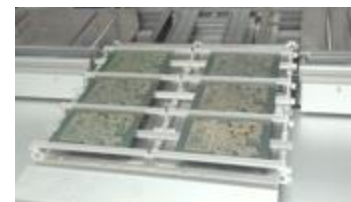
The VAC Inline Series is an environmentally friendly and flexible soldering system dedicated for highest quality soldering. This machine can be fully integrated into a production line and if necessary also be used in the batch mode. The patented vacuum chamber located in the process chamber ensures that highest solder quality with a minimum amount and size of voids is possible. Outstanding performance and quality results through the unique technology applied in these machines. Regardless of the number of layers in the board and high mix of components this machine can handle the toughest applications with fantastic results. The Intelligent Profiling System gives the user full control of temperature rise to reach the best and desired soldering profiles. Together with the unique patented Soft Vapour Phase there is no fear of exceeding temperature increase rates of components. Their outstanding low energy consumption and exhaust air volume compared to other soldering systems result in even lower running costs. Excellent heat transfer in an inert oxygen free atmosphere without the need of costly nitrogen. Two chamber system with a large touch display makes this machine user friendly, easy to set up and use. Soldering is possible regardless of assembly weight with the same profile.



Automatic board handling



Automatic lane adjustment



Loaded Work Piece Carrier

Features:

- Comfortable 15" Touch-Screen mounted on a swiveling arm
- Integrated PC, allows permanent data collection and professional data management
- Permanent data collection
- Unlimited program memory with a large amount of sample programs
- Network capable
- Password protected operation levels
- Heating power monitoring
- Energy management system
- Intelligent Profiling System (IPS) for high-end thermal profile control
- Buffer in the loading and unloading areas
- Automatic loading and unloading Work Piece Carrier
- Patented vibration and maintenance free transport system
- Two chamber design and medium recovery results in a very low fluid consumption
- Fluid level control and automatic filtering
- Patented vacuum chamber design inside of the process chamber
- Controllable vacuum generation set up in steps, multi vacuum or linear mode
- Integrated fans with global bottom cooling
- Minimal maintenance and wear due to all moving parts mounted outside of the process chamber
- Easy access to solder chamber for cleaning and maintenance purposes
- Observation window into the solder chamber
- Signal light tower
- Exhaust connection
- Cool handling – transport system in cool area

Options:

Process extensions

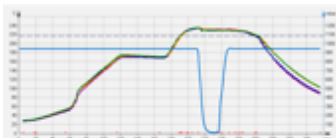
- Infrared pre-heating
- Vapour descent
- Extended pcb cooling
- Patented Rapid Cooling System (RCS)
- Up to 3 additional temperature measurement channels
- Multi-Level Mode for rapid switching between different soldering heights
- Nitrogen flooding of the cooling and process chamber

Software extensions

- Online Temperature Recording Software (TRS) for data analysis and storage including alarm and event log
- Pilot mode, measurement channel for easy temperature-controlled soldering and setting up of profiles
- Various traceability extensions, for automated processes and tracking, ready for Industry 4.0

Hardware extensions

- Automatic adjustment of transport lane width and work piece carrier
- Larger transport width
- Measurement carrier for thermal profiling
- Wireless 6-Channel Profiler for thermal profiling during vacuum phase
- Batch carrier and stainless-steel grid
- Adapter for double sided boards on batch carrier
- TE-Adapter for simple plug-in of PCB-thermocouples
- Heavy Duty "HD" model for loads up to 14 kg with stronger heating capabilities
- Exhaust system extensions and 2nd Emergency stop button
- UPS – Uninterruptable Power Supply
- ReSy – a device for repair of QFPs and BGAs
- Expanded medium filter system including medium levelling and fast cooling system
- Noise protection for vacuum tower
- Storage compartment for carrier
- Integration of a bypass system
- Chiller for inside or outside use with automatic standby control



Real time profile monitoring



Machine status monitor



Vacuum unit inside of process chamber

Technical data:

	VAC745i	VAC765i
Width	2040 mm - (80.31")	
Depth	3040 mm - (119.69")	3450 mm - (135.83")
Height	1470 mm - (57.87")	
Weight	1290 kg (2843.96 lbs)	1450 kg (3196.70 lbs)
Max. PCB size inline modus	630 x 400 x 50 mm (24.80 x 15.75 x 1.97") with vacuum 630 x 400 x 60 mm (24.80 x 15.75 x 2.36") without vacuum	
Max. PCB size batch modus	635 x 444 x 70 (25.00 x 17.48 x 2.76") with vacuum 635 x 444 x 80 mm (25.00 x 17.48 x 3.15") without vacuum	635 x 644 x 70 mm (25.00 x 35.35 x 2.76") with vacuum 635 x 644 x 80 mm (25.00 x 25.35 x 3.15") without vacuum
Max. load on single carrier	7 kg (15.43 lbs)	
Liquid agent filling	40 kg (88.18 lbs)	60 kg (132.28 lbs)
Water connection	1/2" / 2.5 - 5 bar	
Max. heating capacity	10.4 kW	13 kW
Average power consumption	5.5 kW/h	5.8 kW/h
Power supply	400 / 230 VAC, 50Hz	
Main fuse	32A „gI“ or „C“	32A „gI“ or „C“
External vacuum module	910 x 550 x 650mm (35.83 x 21.65 x 25.59"), 119 kg (262.35 lbs)	

Specifications subject to change without prior notice

D1E127-Datasheet VAC7x5i E-211108